



Material Content Data Sheet



Sales Product Name		BSO150N03MD G		Issued		27. September 2017		
MA#		MA000468352						
Package		PG-DSO-8-40		Weight*		82.45 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.061	1.29	1.29	12874	12874
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		119	
	non noble metal	zinc	7440-66-6	0.039	0.05		476	
	non noble metal	iron	7439-89-6	0.785	0.95		9523	
wire	non noble metal	copper	7440-50-8	31.880	38.67	39.68	386656	396774
	non noble metal	copper	7440-50-8	0.262	0.32	0.32	3173	3173
	encapsulation	organic material	carbon black	1333-86-4	0.235	0.28		2850
encapsulation	plastics	epoxy resin	-	7.284	8.83		88340	
	inorganic material	silicondioxide	60676-86-0	39.474	47.87	56.98	478748	569938
leadfinish	non noble metal	tin	7440-31-5	0.814	0.99	0.99	9870	9870
plating	noble metal	silver	7440-22-4	0.063	0.08	0.08	762	762
glue	plastics	epoxy resin	-	0.082	0.10		991	
	noble metal	silver	7440-22-4	0.463	0.56	0.66	5618	6609
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com